



(43) International Publication Date
2 October 2014 (02.10.2014)

(10) International Publication Number
WO 2014/159170 A1

- (51) **International Patent Classification:**
H05B 33/02 (2006.01) *G09F 9/00* (2006.01)
G02F 1/00 (2006.01)
- (21) **International Application Number:**
PCT/US2014/022340
- (22) **International Filing Date:**
10 March 2014 (10.03.2014)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
- (30) **Priority Data:**
61/781,872 14 March 2013 (14.03.2013) US
- (71) **Applicant:** CORNING INCORPORATED [US/US]; 1 Riverfront Plaza, Corning, New York 14831 (US).
- (72) **Inventors; and**
- (71) **Applicants :** BOWDEN, Bradley Frederick [US/US]; 223 East Pulteney Street, Corning, New York 14830 (US). ELLISON, Adam James [US/US]; 70 E. 5th Street, Corning, New York 14830 (US). WEEKS, Wendell Porter [US/US]; 10806 Hidden Meadow Trail, Corning, New York 14830 (US).
- (74) **Agent:** SCHMIDT, Jeffrey A.; Corning Incorporated, Intellectual Property Department, SP-Ti-03-01, Corning, New York 14831 (US).

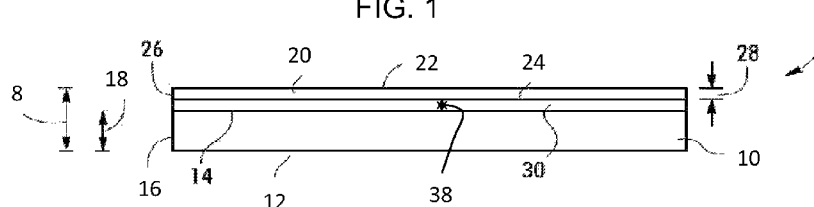
- (81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JP, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.
- (84) **Designated States** (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) **Title:** METHODS OF PROCESSING ELECTRONIC DEVICES

FIG. 1



(57) **Abstract:** A method of processing electronic devices includes obtaining an article (2) having a thin glass sheet (20) coupled to a carrier (10) that has a first QCOLED compaction value. The article is subjected to a first processing cycle (P1) to form a first device (40) on the thin glass sheet, wherein after the first processing cycle, the carrier has a second QCOLED compaction value that is less than the first QCOLED compaction value. The thin glass sheet is removed (P2) from the carrier. Subsequently, the carrier is subjected to a second processing cycle (P4) to form a second device (50) thereon, wherein during the second processing cycle a maximum processing temperature used is not the same as that used during the first processing cycle. Instead of forming second devices on the carrier, a second thin sheet (220) may be coupled to the carrier and third devices (60) processed thereon.